

# Fair-Rite P/N **2952778301**

## 52 Material Grade

## Nominal Chemical Composition

### Supporting notes:

1. P/N 2952778301 consists of:
  - a core 52 Material Grade
  - b wire Pb- Free Plated Round Cu Wire
  - c epoxy Type EP399 Epoxy
2. Moisture Sensitivity Level (MSL)= 1
3. Max Reflow Temp= 260 degC
4. Max Time at Max Reflow Temp= 40 sec
5. RoHS 6/6 Compliant Terminations/ Wire are backwards compatible with standard Soldering Processes
6. RoHS Conversion Date= 1/1/2005
7. RoHS Compliance Marking is Contained on Shipping Labels

<u>Compound</u>	<u>CAS Number</u>	<u>wt %</u>	Wt of core (g)= <b>5.490</b>	Compound Weight (g) Breakdown of 52 Material
Fe2O3	1309-37-1	63	3.4586	
ZnO	1314-13-2	17	0.9333	
NiO	1313-99-1	14	0.7686	
CuO	1317-38-0	5	0.2745	
CoO	1307-96-6	1	0.0549	

## Pb- Free Plated Round Cu Wire

<u>Element</u>	<u>CAS Number</u>	<u>wt%</u>	Wt of wire (g)= <b>0.420</b>	Element Weight (g) Breakdown of Pb-Free Plated Round Cu Wire
Cu	7440-50-8	94.4	0.39648	
Plating:				
Ni	7440-02-0	0.9	0.00378	
Sn	7440-31-5	4.7	0.01974	

## Type EP399 Epoxy

<u>Element</u>	<u>CAS Number</u>	<u>wt%</u>	Wt of Epoxy (g)= <b>0.090</b>	Element Weight (g) Breakdown of Type EP399 Epoxy
Epoxy Resin	025085-99-8	45.0	0.04050	
Cyanoguanidine	461-58-5	5.0	0.00450	
Silica	7631-86-9	5.0	0.00450	
Aluminum Hydroxide	21645-51-2	35.0	0.03150	
Carbon Black	1333-86-4	10.0	0.00900	

## Calculated Maximum Levels of RoHS Restricted Substances Present in 52 Material Grade

<u>Impurity Substance</u>	<u>RoHS Threshold (ppm)</u>	<u>ppm</u>	Wt of core (g)= <b>5.490</b>	RoHS Impurity Substance Weight (g) Breakdown of 52 Material
Cr+6	1000	0.00	0	
Cd	100	<b>6.09</b>	3.34341E-05	
Hg	1000	<b>0.09</b>	4.941E-07	
Pb	1000	<b>10.90</b>	0.000059841	
PBB	1000	0.00	0	
PBDE	1000	0.00	0	